



# SOT804-5

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals

8 February 2016

Package information

## 1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN64
Package type industry code	HVQFN64
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	30-8-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	64	-	

## 2. Package outline

Fig. 1. Package outline HVQFN64 (SOT804-5)



### 3. Legal information

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